

ABSTRACT**OPTOELECTRONIC BALL GRID ARRAY PACKAGE WITH FIBER**

A photonic integrated circuit may be coupled to an optical fiber and packaged. The optical fiber may be supported by a fiber holder during a solder reflow process performed to mount the packaged photonic integrated circuit to a circuit board or other substrate. The optical fiber may be decoupled from the fiber holder, and the fiber holder removed, after completion of the solder reflow process.

FIG. 2A